

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

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(Engineering Calculation)

QFN 3mm X 3mm Exp. Pad

(printed on: 2020-07-11 17:42:51)

**TOTAL MASS (g) : 0.02262**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.000605	1000000	26746.5253906		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.008752	975000	386918.34375		
		Iron (Fe)	7439-89-6	0.000215	24000	9504.96386719		
		Phosphorus (P)	7723-14-0	0.000003	300	132.627410889		
		Zinc (Zn)	7440-66-6	0.000006	700	265.254821777		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.008976</b>	<b>1000000</b>	<b>396821.1875</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.000413	1000000	18247.8144531		
		<b>External Plating Total:</b>				<b>0.000413</b>	<b>1000000</b>	<b>18247.8144531</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000203	1000000	8974.45410156		
<b>Internal Plating Total:</b>				<b>0.000203</b>	<b>1000000</b>	<b>8974.45410156</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000419	750000	18523.6269531		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000140	250000	6189.27880859		
<b>Die Attach Total:</b>				<b>0.000559</b>	<b>1000000</b>	<b>24712.90625</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.001534	130000	67816.8125		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.010148	860000	448634.28125		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000118	10000	5216.67822266		
		<b>Encapsulation Total:</b>				<b>0.011800</b>	<b>1000000</b>	<b>521667.78125</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000064	1000000	2829.38452148		
					<b>TOTAL MASS (g) :</b>	<b>0.02262</b>		